

WE CLAIM:

1. A printed circuit board arrangement with a flexible layer arrangement, in which at least one electrically conductive layer with a large number of conductor tracks lying next to one another is accommodated and surrounded by electrically isolating layers, the flexible layer arrangement being firmly connected in portions to at least one printed circuit board suitable for accommodating a component for forming a fixed portion, and an opening extending as far as the conductor tracks being provided in the region of the fixed portion, the improvements comprising the clearance passing through the printed circuit board to enable contacting the conductor tracks with the component.

2. A printed circuit board arrangement according to claim 1, which has a plurality of electrically conductive layers being arranged one on top of the other and being separated from one another by electrically isolating layers in the flexible layer arrangement.

3. A printed circuit board arrangement according to claim 2, wherein the opening being formed is in a step-like manner so that the conductor tracks of more than one layer can be contacted.

4. A printed circuit board arrangement according to claim 1, wherein an electrically conductive layer situated closest to the surface of the flexible layer is formed as a shielding layer.

5. A printed circuit board arrangement according to claim 1, wherein the electrically isolating layers are produced from a polyamide.

6. A printed circuit board arrangement according to claim 1, wherein the component has a large number of photodiodes.

7. A printed circuit board arrangement according to claim 6, wherein a fixed portion has a metal layer and one of the two contacts of each of the photodiodes is respectively connected to the metal layer.

8. A printed circuit board arrangement according to claim 7, wherein the other contact of each photodiode is connected to a conductor track provided for this purpose.

9. A printed circuit board arrangement according to claim 8, wherein a connection of the other contact to the conductor track is by means of a bonding technique directly between the other contact and the conductor track.

10. A printed circuit board arrangement according to claim 9, wherein the opening, after forming the electrical connections, is filled with a casting compound.

11. A printed circuit board arrangement according to claim 10, wherein the casting compound is a plastic.

12. A printed circuit board arrangement according to claim 1, wherein the component on the at least one printed circuit board is a detector module for an X-ray computer tomograph.

13. A printed circuit board arrangement according to claim 1, wherein the opening, after forming the connection, is filled with a casting compound.

14. A printed circuit board arrangement according to claim 13, wherein the casting compound is a plastic.

15. A printed circuit board arrangement according to claim 1, which includes a metal layer being applied on the fixed portion and a contact of the component being connected to the metal layer and another contact of the component being connected to the conductor track by means of a bonding technique.

15. A printed circuit board arrangement according to claim 1, which includes a metal layer being applied on the fixed portion and a contact of the component being connected to the metal layer and another contact of the component being connected to the conductor track by means of a bonding technique.